### TISP4CxxxH3BJ Overvoltage Protector Series

### BOURNS®

### Absolute Maximum Ratings, T<sub>A</sub> = 25 °C (Unless Otherwise Noted)

Rating		Symbol	Value	Unit
Repetitive peak off-state voltage	*4C115H3BJ *4C125H3BJ *4C145H3BJ *4C165H3BJ *4C180H3BJ *4C220H3BJ *4C220H3BJ *4C250H3BJ *4C350H3BJ *4C395H3BJ	V <sub>DRM</sub>	±90 ±100 ±120 ±135 ±145 ±180 ±190 ±220 ±275 ±320	v
Non-repetitive peak impulse current (see Notes 1 and 2) 2/10 μs (GR-1089-CORE, 2/10 μs voltage wave shape) 10/160 μs (TIA-968-A, 10/160 μs voltage wave shape) 5/310 μs (ITU-T K.44, 10/700 μs voltage wave shape used in K.20/21/45) 10/560 μs (TIA-968-A, 10/560 μs voltage wave shape) 10/1000 μs (GR-1089-CORE, 10/1000 μs voltage wave shape)		I <sub>PPSM</sub>	±500 ±200 ±150 ±100 ±100	A
Non-repetitive peak on-state current (see Notes 1, 2 and 3) 20 ms, 50 Hz (full sine wave) 1000 s, 50 Hz		I <sub>TSM</sub>	30 2.1	А
Junction temperature		TJ	-40 to +150	°C
Storage temperature range		T <sub>stg</sub>	-65 to +150	°C

NOTES: 1. Initially the device must be in thermal equilibrium with  $T_J = 25$  °C.

2. The surge may be repeated after the device returns to its initial conditions.

3. EIA/JESD51-2 environment and EIA/JESD51-3 PCB with standard footprint dimensions connected with 5 A rated printed wiring track widths.

#### Electrical Characteristics, T<sub>A</sub> = 25 °C (Unless Otherwise Noted)

	Parameter	Test Conditions		Min	Тур	Max	Unit
I <sub>DRM</sub>	Repetitive peak off-state current	$V_{D} = V_{DRM}$	T <sub>A</sub> = 25 °C T <sub>A</sub> = 85 °C			±5 ±10	μΑ
V <sub>(BO)</sub>	Breakover voltage	dv/dt = ±250 V/ms, $R_{SOURCE}$ = 300 $\Omega$	'4C115H3BJ '4C125H3BJ '4C145H3BJ '4C165H3BJ '4C180H3BJ '4C220H3BJ '4C220H3BJ '4C250H3BJ '4C290H3BJ '4C350H3BJ '4C395H3BJ			$\pm 115$ $\pm 125$ $\pm 145$ $\pm 165$ $\pm 220$ $\pm 220$ $\pm 250$ $\pm 290$ $\pm 350$ $\pm 395$	v
V <sub>(BO)</sub>	Impulse breakover voltage	dv/dt ≤ ±1000 V/μs, Linear voltage ramp, Maximum ramp value = ±500 V di/dt = ±10 A/μs, Linear current ramp, Maximum ramp value = ±10 A	'4C115H3BJ '4C125H3BJ '4C145H3BJ '4C165H3BJ '4C180H3BJ '4C220H3BJ '4C250H3BJ '4C290H3BJ '4C350H3BJ '4C395H3BJ			$\pm 125$ $\pm 135$ $\pm 155$ $\pm 175$ $\pm 190$ $\pm 230$ $\pm 260$ $\pm 300$ $\pm 360$ $\pm 405$	v
I <sub>(BO)</sub>	Breakover current	dv/dt = $\pm 250$ V/ms, R <sub>SOURCE</sub> = 300 $\Omega$				±600	mA
V <sub>T</sub>	On-state voltage	I <sub>T</sub> = ±5 A,t <sub>w</sub> = 100 μs				±3	V
Ι <sub>Η</sub>	Holding current	$I_T = \pm 5 \text{ A}, \text{ di/dt} = \pm 30 \text{ mA/ms}$		±150		±600	mA
	Off-state capacitance	f = 1 MHz, V <sub>d</sub> = 1 V rms, V <sub>D</sub> = -2 V	'4C115H3BJ '4C125H3BJ			50	
Co			'4C145H3BJ '4C165H3BJ '4C180H3BJ '4C220H3BJ '4C250H3BJ			45	pF
			'4C290H3BJ '4C350H3BJ '4C395H3BJ			40	

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#### Thermal Characteristics, T<sub>A</sub> = 25 °C (Unless Otherwise Noted)

	Parameter	Test Conditions	Min	Тур	Max	Unit
R <sub>θJA</sub>	Junction to ambient thermal resistance	EIA/JESD51-3 PCB, I <sub>T</sub> = I <sub>TSM(1000)</sub> (see Note 4)			113	°C/W
		265 mm x 210 mm populated line card, 4-layer PCB, $I_T = I_{TSM(1000)}$		50		C/W

NOTE: 4. EIA/JESD51-2 environment and PCB has standard footprint dimensions connected with 5 A rated printed wiring track widths.

#### **Parameter Measurement Information**

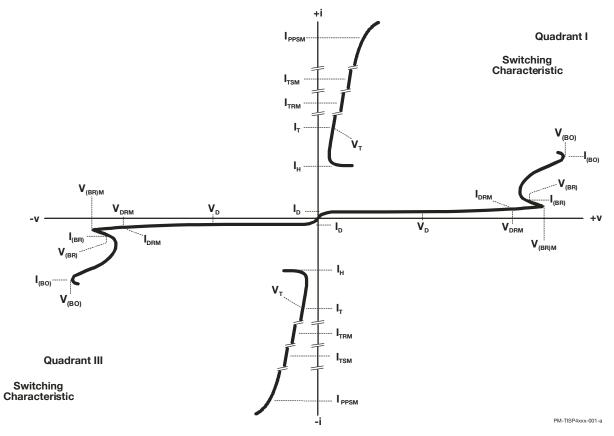


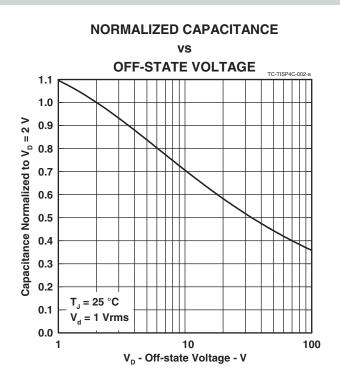
Figure 1. Voltage-Current Characteristic for T and R Terminals All Measurements are Referenced to the R Terminal

SEPTEMBER 2004 – REVISED JUNE 2007 Specifications are subject to change without notice. Customers should verify actual device performance in their specific applications.

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**Typical Characteristics** 



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